NC PASTE/TACKY FLUX

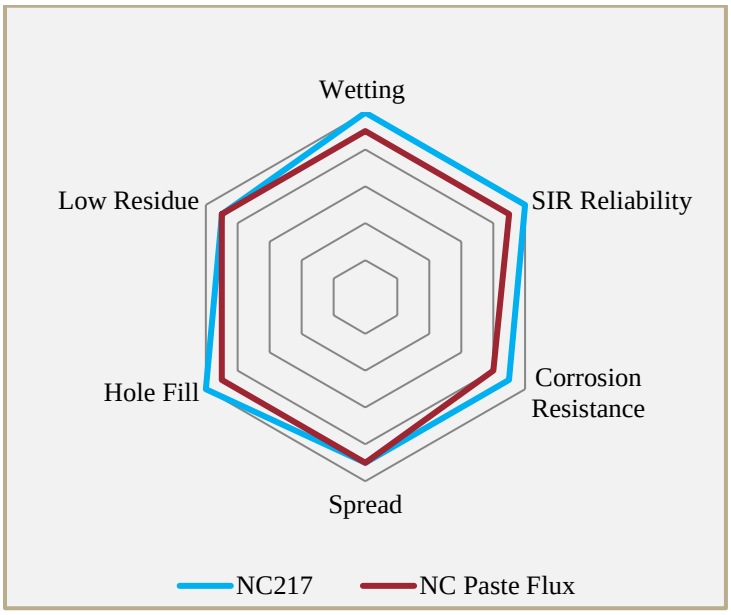
FEATURES

- Halogen/Halide-Free
- Low Voiding
- Wide Process Window
- Tin-Lead and Lead-Free Compatible
- Compliant to IPC 7711-7721 Rework/Repair Modification
- High Tack Force for Component Mass Transfer Processes

DESCRIPTION

NC Paste Flux is a no clean tacky/rework flux designed for rework, BGA sphere attach and mass transfer processes. NC Paste Flux can be used in all reflow processes from hand soldering to vapor phase reflow. NC Paste Flux residues do not require removal. NC Paste Flux is compatible with all tin-lead and lead-free alloys. NC Paste Flux can be dispensed, stencil printed or hand applied. NC Paste Flux complies with the IPC 7711-7721 standard.

CHARACTERISTICS



HANDLING & STORAGE

PARAMETER	TIME	TEMPERATURE
Sealed Refrigerated Shelf Life	1 Year	0°C-12°C (32°F-55°F)
Sealed Unrefrigerated Shelf Life	6 Months	< 25°C (< 77°F)

NC Paste Flux has a sealed shelf life of one (1) year when stored 0°C-12°C (32°F-55°F). Do not store near fire or flame. Keep away from sunlight as it may degrade product. NC Paste Flux is shipped ready-to-use, no mixing necessary. Do not mix used and unused chemicals in the same container. Reseal any opened containers. After opening, paste flux shelf life is environment and application dependent.

APPLICATION

NC Paste Flux is ready to use directly from its container, no thinning required. NC Paste flux is typically dispensed, swabbed or brushed onto the workpiece.

PROCESS GUIDELINES

NC paste flux should be processed according to the alloy and application requirements. For application support, please contact AIM by visiting http://www.aimsolder.com/technical-support-contacts.

*All information for reference only. Not to be used as incoming product specifications or for process design. Consult Certificate of Analysis for product specific information.

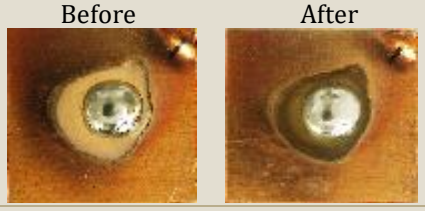
CLEANING

NC Paste Flux can be cleaned using commercially available flux removers. Contact AIM for additional information.

SAFETY

Use with adequate ventilation and proper personal protective equipment. Refer to the accompanying Safety Data Sheet for any specific emergency information. Do not dispose of any hazardous materials in non-approved containers.

TEST DATA SUMMARY

NAME	TEST METHOD	RESULTS	
IPC Flux Classification	J-STD-004	ROL0	
IPC Flux Classification	J-STD-004B 3.3.1	ROL0	
NAME	**TEST METHOD**	**RESULTS**	**IMAGE**
Copper Mirror	J-STD-004B 3.4.1.1 IPC-TM-650 2.3.32	LOW	
Corrosion	J-STD-004B 3.4.1.2 IPC-TM-650 2.6.15	PASS	Before After 
Quantitative Halides	J-STD-004B 3.4.1.3 IPC-TM-650 2.3.28.1	0.0%	
Qualitative Halides, Silver Chromate	J-STD-004B 3.5.1.1 IPC-TM-650 2.3.33	PASS	
Qualitative Halides, Fluoride Spot	J-STD-004B 3.5.1.2 IPC-TM-650 2.3.35.1	No Fluoride	

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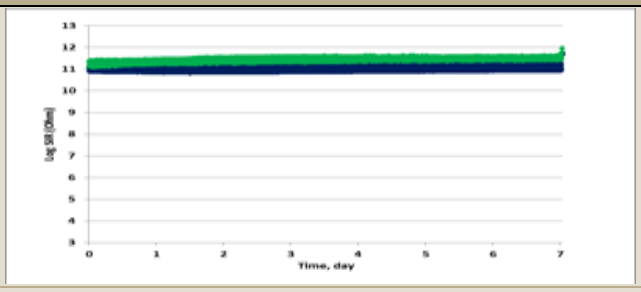
NAME	TEST METHOD	RESULTS	IMAGE
Surface Insulation Resistance	J-STD-004B 3.4.1.4 IPC-TM-650 2.6.3.7	All measurements on test patterns exceed 100 MΩ	
Acid Value Determination	J-STD-004B 3.4.2.2 IPC-TM-650 2.3.13	161 ± 3 mgKOH/g flux Typical	
Visual	J-STD-004B 3.4.2.5	PASS	
Wetting	J-STD-005A 3.9 IPC-TM-650 2.4.45	PASS	
Tack	JIS 3284.9	180gf	

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